

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|---------------------|
| L1 | 1245 | 174/254.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:01 |
| L2 | 12 | 1 and flexible adj wiring adj substrate or FWB and insulating adj substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:14 |
| L3 | 822 | flexible adj wiring adj substrate or FWB and insulating adj substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:15 |
| L4 | 2 | 3 and wiring adj pattern and solder adj resist adj layer and tin adj plating adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:17 |
| L5 | 10 | wiring adj pattern and solder adj resist adj layer and tin adj plating adj layer and flexible adj wiring adj substrate or FWB and insulating adj substrate | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:19 |

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|-----|-----|---|---|----|----|---------------------|
| L6 | 814 | flexible adj wiring adj substrate or FWB and insulating adj substrate and wiring adj pattern and solder adj resist adj layer and tin adj plating adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:20 |
| L14 | 113 | Insulating adj substrate and wiring adj pattern and solder and wiring adj pattern and wiring adj pattern same multilayer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:29 |
| L15 | 17 | Insulating adj substrate and wiring adj pattern and solder and wiring adj pattern and wiring adj pattern same multilayer and solder adj resist adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:30 |
| L16 | 9 | Insulating adj substrate and wiring adj pattern and solder and wiring adj pattern and wiring adj pattern same multilayer and solder adj resist adj layer and plating adj layer and | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:31 |

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|-----|---|--|---|----|----|---------------------|
| | | multilayer | | | | |
| L17 | 1 | Insulating adj substrate and wiring adj pattern and solder and wiring adj pattern and wiring adj pattern same multilayer and solder adj resist adj layer and plating adj layer and multilayer and copper adj layer | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/07 14:32 |

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